

21st European Wet & 50th European CMP User Group Meeting

Wet- and CMP-Session: Thursday, April 23, 2026, 13:00 – 18:00

CMP-Session: Friday, April 24, 2026, 8:00 – 13:00

Hotel Domero congress center, Halle (Saale), Germany

Organized by European CMP&WET User Group and supported by SONOTEC

Agenda Thursday, April 23rd

12:00 – 13:30 Welcome Coffee, Tea, Softdrinks and Snacks

13:30 Opening Remarks & Welcome
Knut Gottfried
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

Wet Session 1

Session Chair: Knut Gottfried, Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany

13:40 Theoretical Consideration of the Speed of Sound Influence on Ultrasonic Sensors in Liquids
Maik Christl
SONOTEC GmbH, Halle (Saale), Germany

14:05 Evaluating Non-TMAH Solvents for Sustainable Stripping of Photoresist Materials
Salem Nasraoui¹, Ronny Tepper¹, Katharina Lilienthal², Steffen Rosenow¹, Celin Richter¹
¹intelligent fluids, Leipzig, Germany, ²Fraunhofer IPMS, Dresden Germany

14:30 Brasable Metal Full Wet Etch Process Optimization on SiC
Dario Tenaglia
STMICROELECTRONICS, Agrate, Italy

14:55 Integrated Inductive Metrology for Wet Chemical Processing — From Pre-Etch Qualification to Post-Etch Verification
Michael Hofmann, Daniel Schmidt, and Marcus Klein
SURAGUS GmbH, Dresden, Germany

15:10 Veeco WaferStorm: WaferEtch in Advanced Packaging Applications
Benedikt Risse
Veeco, Aschheim, Germany

15:25 Company Pitch
ProSys, Gold Sponsor
Igor Eichinger, ProSys, Campbell, CA, USA

15:30 Company Pitch
Sonotec, Co-Organizer
Sebastian Bürkmann, SONOTEC GmbH, Halle (Saale), Germany

15:35 Coffee Break

Wet Session 2 & CMP Session 1

Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany

- 16:10 GreenICT: From TSV Cleaning to Testing a New DMSO/TMAH-Free Stripper for Packaging Applications
Maksym Myndyk, Catharina Rudolph, and Haci Osman Guevenc
Fraunhofer IZM-ASSID, Dresden, Germany
- 16:25 From CMP to Hybrid Bonding: High-Throughput AFM Metrology for Advanced Semiconductor Manufacturing
Christian Bippes, Carolina Paba, Hector Corte, Santiago Andany, Hans Gunstheimer, Jonathan Adams, and Dominik Ziegler
Nanosurf, Liestal, Switzerland
- 16:50 A Planarization System Roadmap for Broadening Device Applications
Ji-Chul Yang
Ebara, Fujisawa, Japan
- 17:15 Advanced Node Process Characterization: Novel Chemical Mechanical Polishing with Environmentally Friendly Abrasive-Free Setup
Felix Köhler¹, Matthias Stender², Nikunj Kumar Visaveliya², and Conrad Guhl¹
¹Fraunhofer IPMS, Dresden, Germany, ²ChEmpower Corporation, Portland, OR, USA
- 17:40 End of Wet Users Meeting / time for networking and discussion
- 18:15 Bus Transfer to SONOTEC
- 19:00 Evening Reception and Dinner at SONOTEC
Opening: Manuela Münch, Michael Münch, Sebastian Bürkmann, Constantin Bartritzek
- 22:30 Bus Transfer back to Hotel Domero

Agenda Friday, April 24th

- 8:30 – 9:00 Good Morning Coffee, Tea, Softdrinks
- 9:00 Opening Remarks: 50th CMP User Group Meeting – A Jubilee
Gerfried Zwicker, Knut Gottfried, Catharina Rudolph, and Martin Kulawski

CMP Session 2

Session Chair: Martin Kulawski, Advaplan, Espoo, Finland

- 9:20 Effluent Slurry Extraction and Analysis in Cu, ILD and Mo CMP During In-Situ Conditioning with Various Types of Gritted Diamond Discs
Ara Philipossian¹, Y. Sampurno¹, A. Warfield², S. Robles², C. Keating², and J.J. Keleher²
¹Araca, Inc., Tucson, AZ, USA; ²Lewis University, Romeoville, IL, USA

- 9:45 Real-Time Inline Monitoring of CMP Slurry Density and Viscosity: Enhancing Process Stability
Sunil Kumar, Joe Goodbread, Tina Griesemer, Vijoya Sa, and Daniel Brunner
Rheonics, Winterthur, Switzerland
- 10:10 Optimization of CMP Process for Copper and SiCN Wafer Hybrid Bonding
Mais Massarwa, Ali Roshanghias, Rodrigues Augusto Daniel, Azeem Syed Munir, and Su MeiRu
Silicon Austria Labs, Villach, Austria / FH Münster, Germany
- 10:35 Image Segmentation - A New Method for Quality Control of High Porosity CMP Pads
Yawen He
Hubei Dinglong Co., Ltd., Wuhan, China
- 11:00 [Company Pitch](#)
Shellback Semiconductor Technology, Gold Sponsor
Tom Parish, Shellback, Coopersburg, PA, USA
- 11:05 [Company Pitch](#)
Ebara, Gold Sponsor
Fabien Durix, Ebara Precision Machinery Europe, Hanau, Germany
- 11:10 **Coffee Break**
- CMP Session 3**
Session Chair: Catharina Rudolph, Fraunhofer IZM-ASSID, Dresden, Germany
- 11:45 Knowledge-Enhanced Process Modelling for CMP
Tom Rothe¹, Jan Langer², and Harald Kuhn²
¹Chemnitz University of Technology, ²Fraunhofer ENAS, Chemnitz, Germany
- 12:10 From Surface Topology to Surface Function: Phase-Space Projections of CMP Process Signatures in a Multiscale Framework
Boris Brodmann
OptoSurf, Ettlingen, Germany
- 12:35 Smarter CMP Control Through Virtual Metrology
Andre Lauff¹, Morten Breidung¹, Peter Thieme¹, and Tom Rothe²
¹Infineon Technologies, Dresden, Germany, ²Chemnitz University of Technology, Chemnitz, Germany
- 12:50 End of CMP User Group Meeting / Time for Networking and Discussion
Coffee, Tea, Softdrinks, and Light Lunch